



TFW

[10191/3964]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Franz LAERMER et al.
Serial No. : 10/530,612
Filed : December 30, 2005
For : **PLASMA SYSTEM AND METHOD FOR
ANISOTROPICALLY ETCHING STRUCTURES
INTO A SUBSTRATE**

Art Unit : 1792
Examiner : Maki A. Angadi
Confirmation No. : 6739

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on

Date: October 1, 2008

Reg. No. 31,792

Signature:

Richard M. Rosati

RESPONSE

SIR:

In response to the Office Action of July 3, 2008, please reconsider, without prejudice, the above-captioned application as follows.

Remarks begin on page 2 of this paper.